



Material Content Data Sheet



Sales Product Name		TLD2310EL		Issued		16. September 2015		
MA#		MA001173206						
Package		PG-SSOP-14-5		Weight*		82.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.376	1.66	1.66	16628	16628
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		416	
	non noble metal	iron	7439-89-6	0.689	0.83		8324	
wire	non noble metal	copper	7440-50-8	27.978	33.80	34.68	338007	346851
	non noble metal	copper	7440-50-8	0.075	0.09	0.09	906	906
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1217
encapsulation	plastics	epoxy resin	-	4.634	5.60		55987	
	inorganic material	silicondioxide	60676-86-0	45.637	55.14	60.86	551354	608558
leadfinish	non noble metal	tin	7440-31-5	0.988	1.19	1.19	11940	11940
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9274	9274
glue	plastics	epoxy resin	-	0.121	0.15		1461	
	noble metal	silver	7440-22-4	0.363	0.44	0.59	4382	5843
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com